

## N-Ch and P-Ch Fast Switching MOSFETs



- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

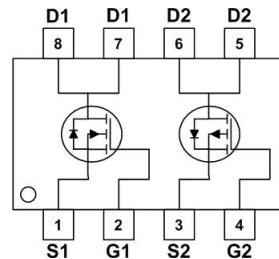
## Product Summary

BVDSS	RDS(ON)	ID
60V	60mΩ	5.0A
-60V	100mΩ	-4.0A

## Description

The XR4612 is the high performance complementary N-ch and P-ch MOSFETs with high cell density, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications. The XR4612 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

## SOP8 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
V <sub>DS</sub>	Drain-Source Voltage	60	-60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	±20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5.0	-4.0	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3.8	-3	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	9.6	-7.5	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	15.5	20.3	mJ
I <sub>AS</sub>	Avalanche Current	12.6	-16.6	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	1.5	1.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	3	°C/W

N-Channel Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.063	---	$\text{V}/\text{ }^\circ\text{C}$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=4\text{A}$	---	60	75	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=2\text{A}$	---	70	95	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	---	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.24	---	$\text{mV}/\text{ }^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{DS}=48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55\text{ }^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=4\text{A}$	---	21	---	S
$R_g$	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	3.2	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=12\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=4\text{A}$	---	5.5	---	$\text{nC}$
$Q_{gs}$	Gate-Source Charge		---	1.8	---	
$Q_{gd}$	Gate-Drain Charge		---	2.4	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=12\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3.3\Omega$ , $I_D=4\text{A}$	---	6	---	$\text{ns}$
$T_r$	Rise Time		---	10	---	
$T_{d(off)}$	Turn-Off Delay Time		---	15	---	
$T_f$	Fall Time		---	7	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	695	---	$\text{pF}$
$C_{oss}$	Output Capacitance		---	148	---	
$C_{rss}$	Reverse Transfer Capacitance		---	7	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	5.0	A
$I_{SM}$	Pulsed Source Current <sup>2,5</sup>		---	---	9.6	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25\text{ }^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25\text{V}$ , $V_{GS}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=5\text{A}$
- 4.The power dissipation is limited by  $150\text{ }^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

## N-Ch and P-Ch Fast Switching MOSFETs

P-Channel Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)

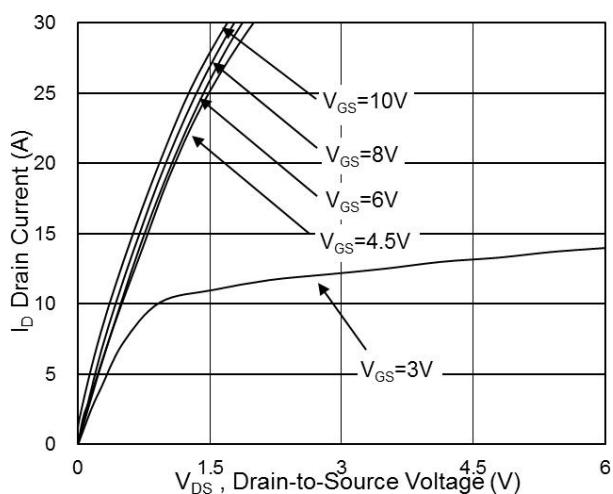
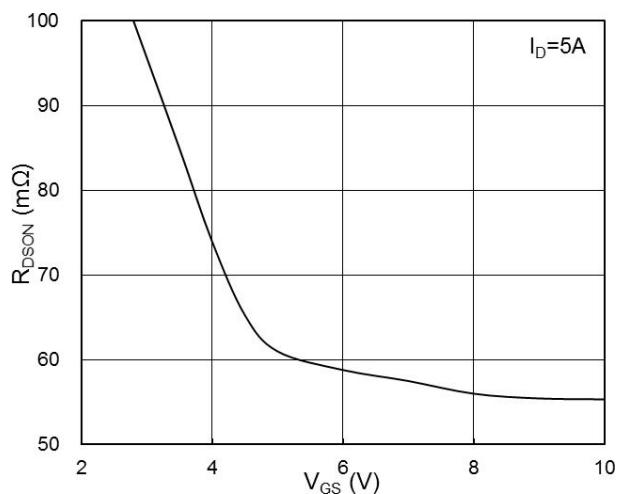
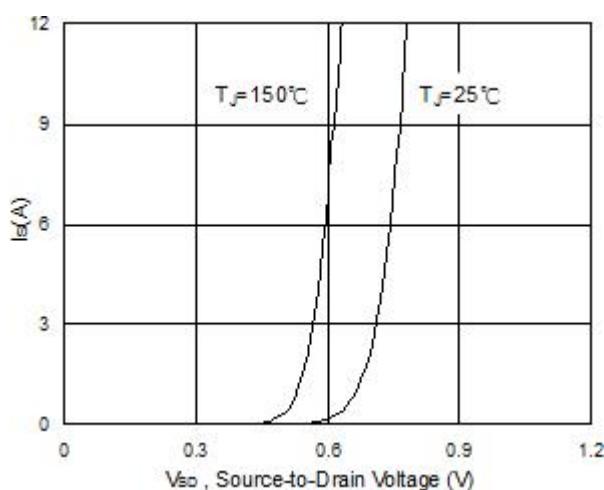
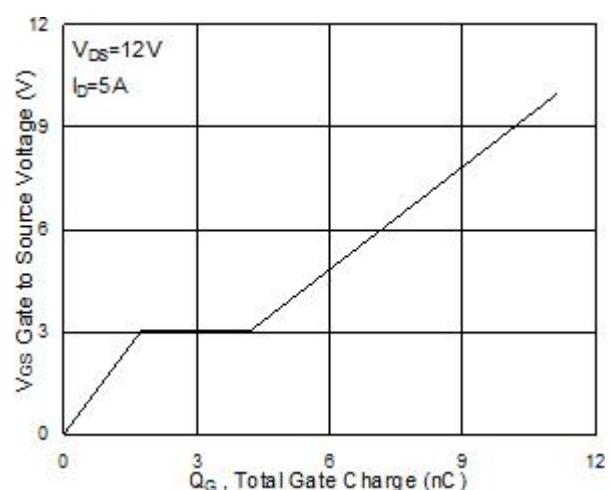
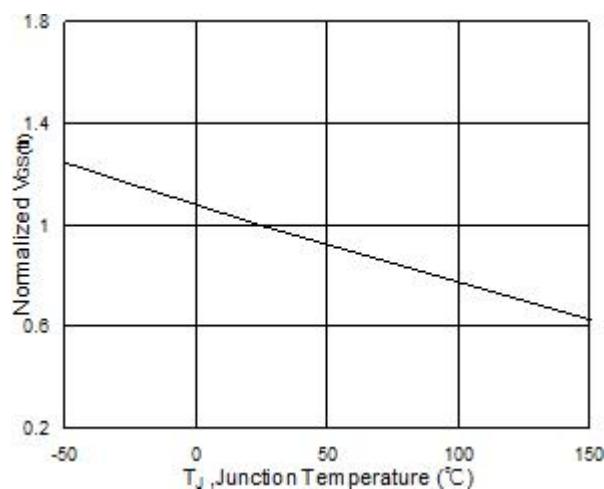
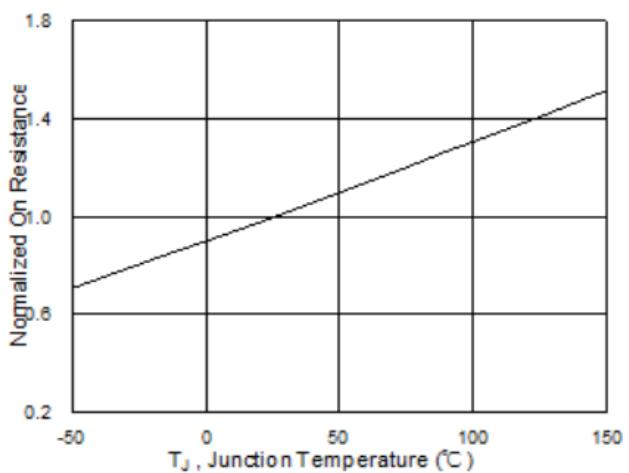
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-60	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.049	---	$\text{V}/\text{ }^\circ\text{C}$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10\text{V}$ , $I_D=-3\text{A}$	---	100	115	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-2\text{A}$	---	115	130	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu\text{A}$	-1.2	---	-2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	4.56	---	$\text{mV}/\text{ }^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25\text{ }^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{DS}=-48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55\text{ }^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 10_0$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=-5\text{V}$ , $I_D=-3\text{A}$	---	5.8	---	S
$R_g$	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	13.5	---	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{DS}=-20\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-3\text{A}$	---	5.9	---	$\text{nC}$
$Q_{gs}$	Gate-Source Charge		---	2.9	---	
$Q_{gd}$	Gate-Drain Charge		---	1.8	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-12\text{V}$ , $V_{GS}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-3\text{A}$	---	10	---	$\text{ns}$
$T_r$	Rise Time		---	17	---	
$T_{d(off)}$	Turn-Off Delay Time		---	22	---	
$T_f$	Fall Time		---	21	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	715	---	$\text{pF}$
$C_{oss}$	Output Capacitance		---	51	---	
$C_{rss}$	Reverse Transfer Capacitance		---	34	---	

## Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-4.0	A
$I_{SM}$	Pulsed Source Current <sup>2,5</sup>		---	---	-7.5	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25\text{ }^\circ\text{C}$	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=-25\text{V}$ , $V_{GS}=-10\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=-20.0\text{A}$
- 4.The power dissipation is limited by  $150\text{ }^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**N-Channel Typical Characteristics****Fig.1 Typical Output Characteristics****Fig.2 On-Resistance v.s Gate-Source****Fig.3 Forward Characteristics of Reverse****Fig.4 Gate-Charge Characteristics****Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$** **Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

## N-Ch and P-Ch Fast Switching MOSFETs

## N-Channel Typical Characteristics

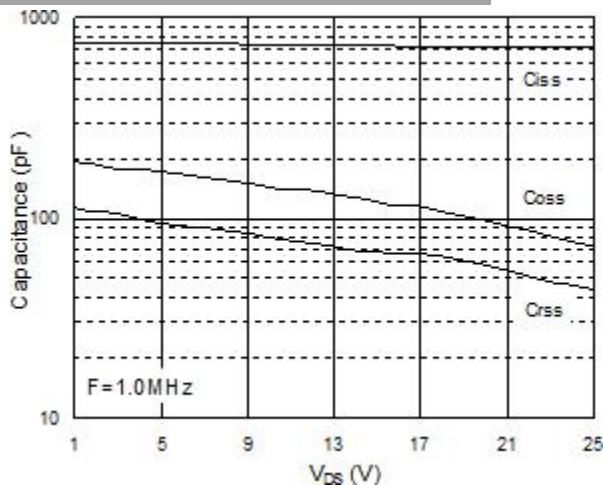


Fig.7 Capacitance

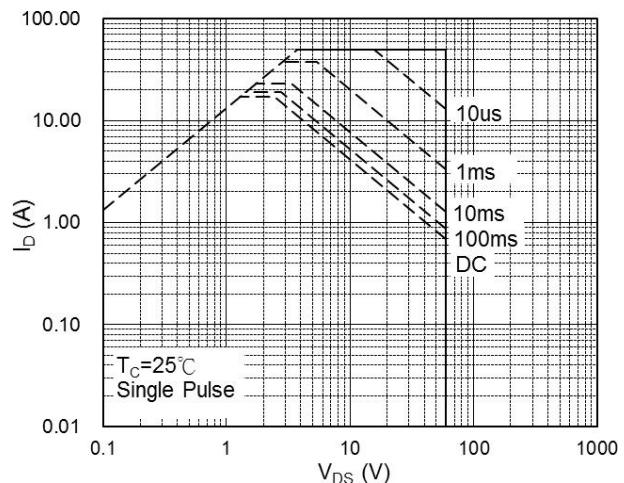


Fig.8 Safe Operating Area

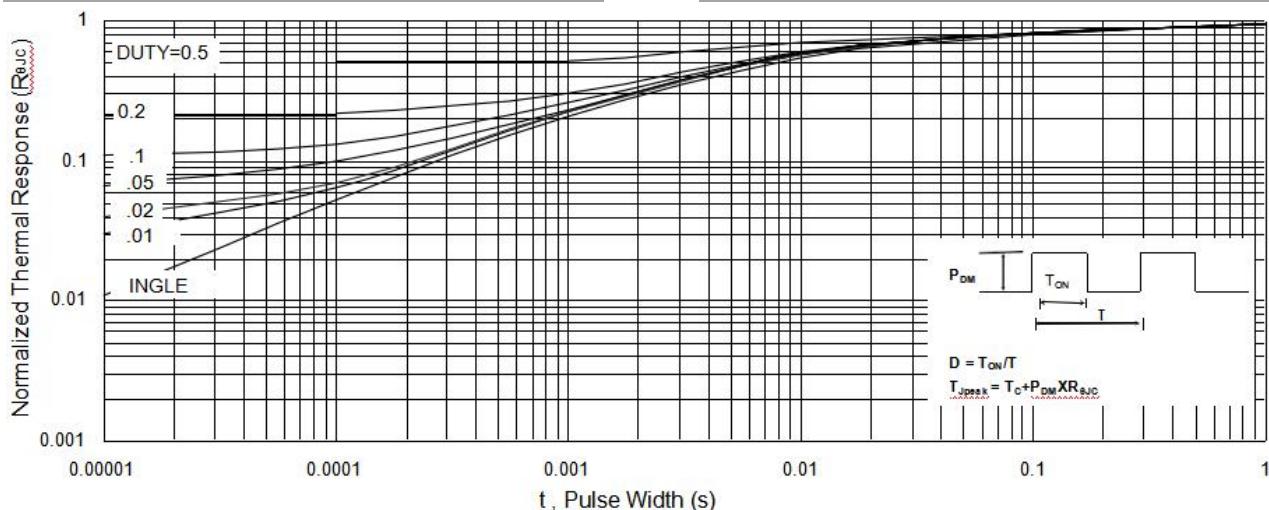


Fig.9 Normalized Maximum Transient Thermal Impedance

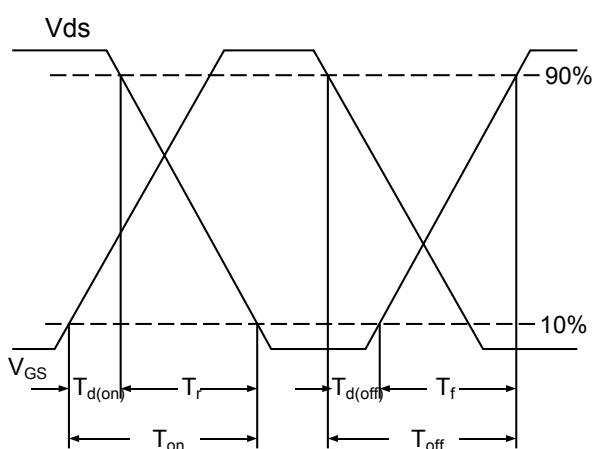


Fig.10 Switching Time Waveform

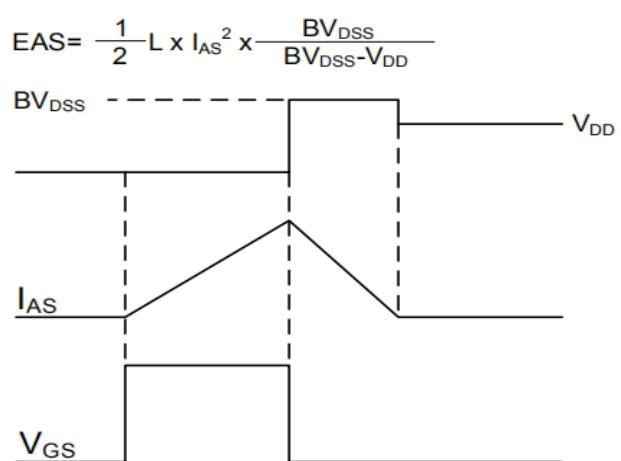


Fig.11 Unclamped Inductive Waveform

## P-Channel Typical Characteristics

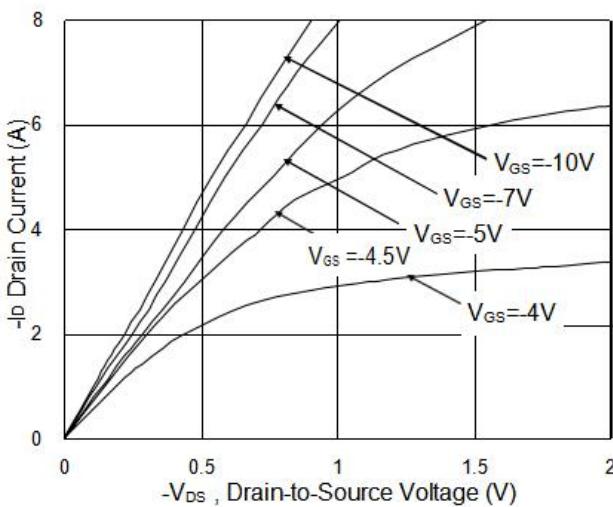


Fig.1 Typical Output Characteristics

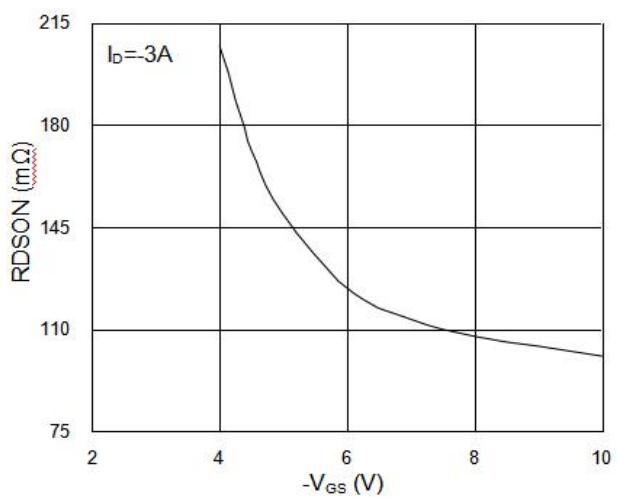


Fig.2 On-Resistance v.s Gate-Source

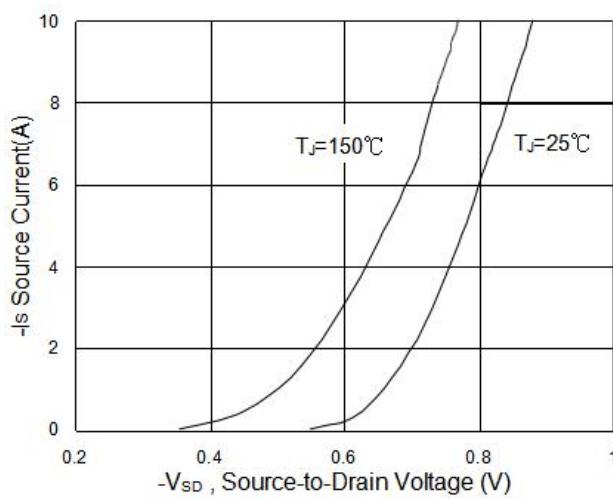


Fig.3 Forward Characteristics of Reverse

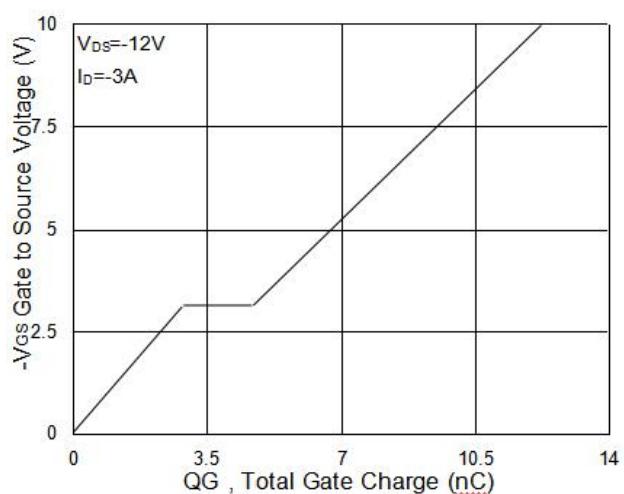
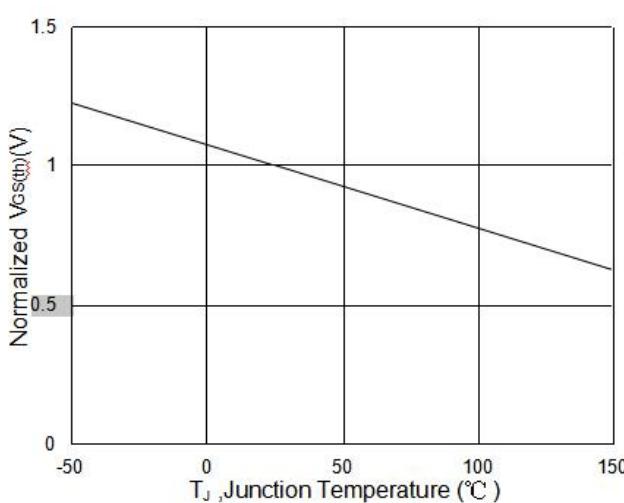
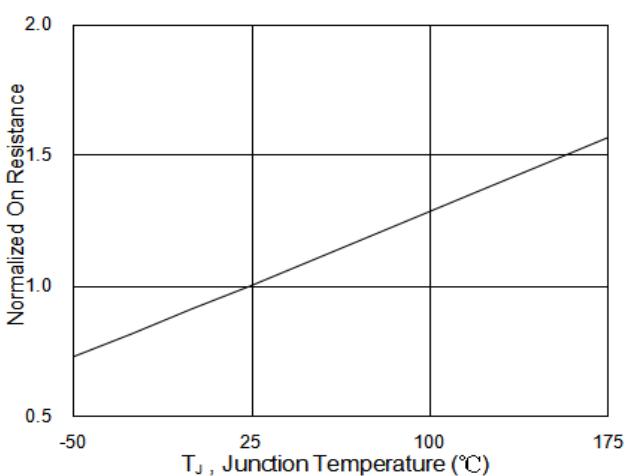


Fig.4 Gate-Charge Characteristics

Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$ Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$

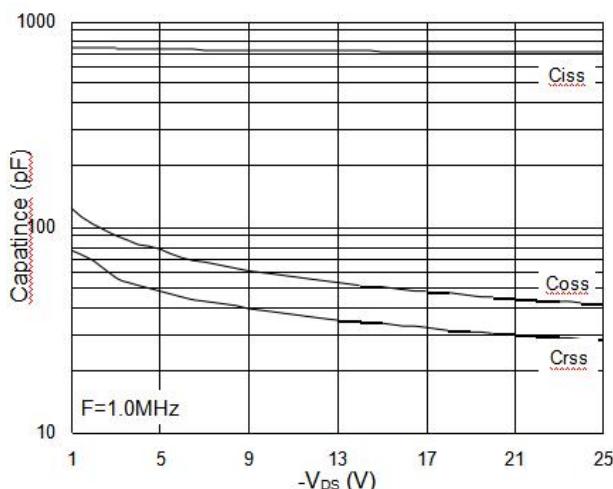


Fig.7 Capacitance

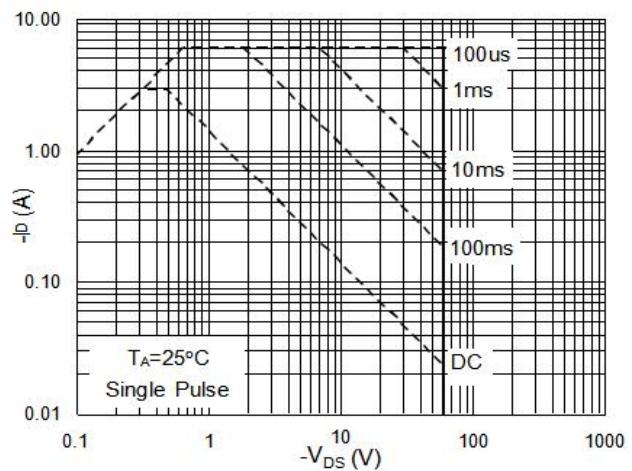


Fig.8 Safe Operating Area

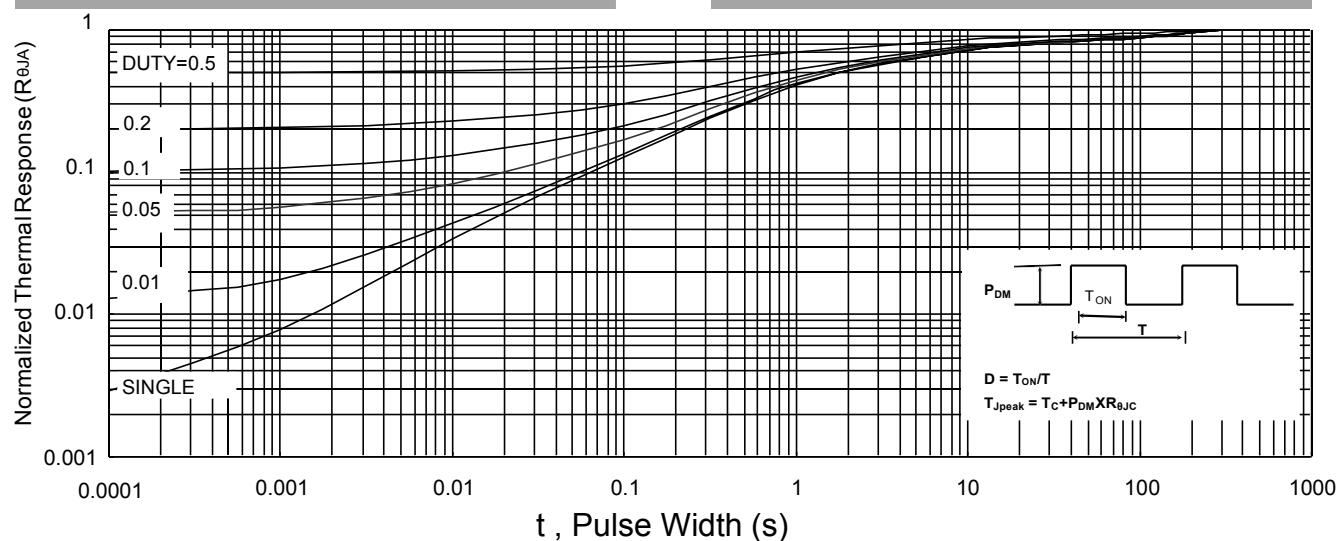


Fig.9 Normalized Maximum Transient Thermal Impedance

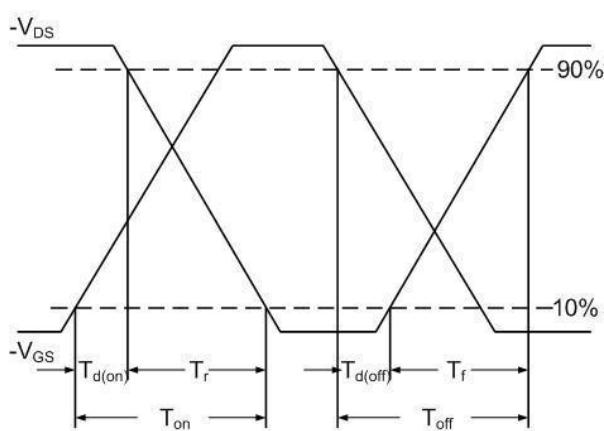


Fig.10 Switching Time Waveform

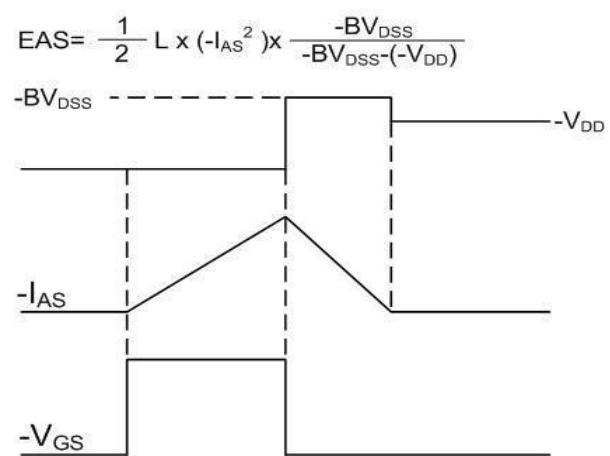
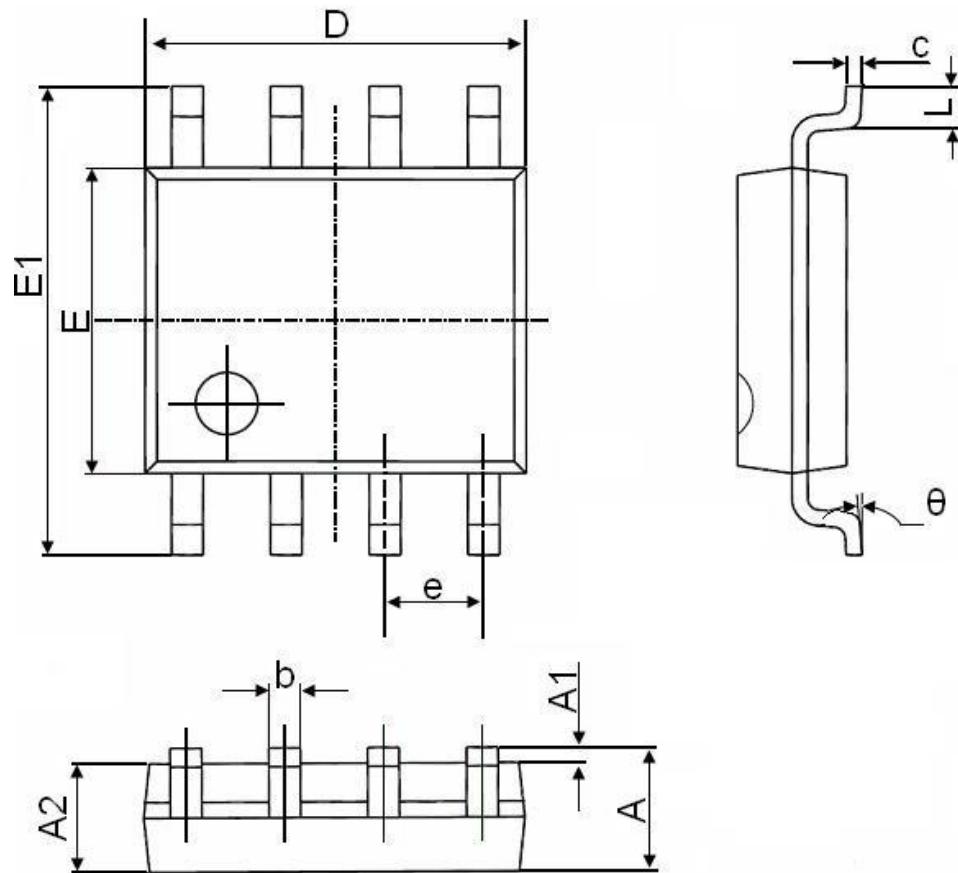


Fig.11 Unclamped Inductive Waveform

## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°